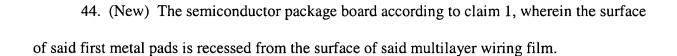
Amendment Under 37 C.F.R. § 1.111 U.S. Appln No. 09/894,123



said multilayer wiring film having a first surface in contact with said metal base plate, said first surface having a plurality of first metal pads in a region of said first surface exposed by said opening in said metal base plate.

Please add the following new claims 42-45:

- 42. (New) The semiconductor package board according to claim 1, wherein said first metal pads comprise a surface which is not in contact with said multilayer wiring film, said surface being coplanar with said multilayer wiring film.
- 43. (New) The semiconductor package board according to claim 1, wherein said first metal pads comprise a surface which is not in contact with said multilayer wiring film, said surface being recessed toward said first surface of said multilayer wiring film.



- 45. (New) A semiconductor package board comprising:
- a metal base plate having an opening; and
- a multilayer wiring film formed on said metal base plate, said multilayer wiring film having a first surface in contact with said metal base plate and mounting thereon a plurality of first metal pads within a region exposed from said opening of said metal base plate, wherein surface of the first metal pads is recessed form the surface of the multilayer wiring film.